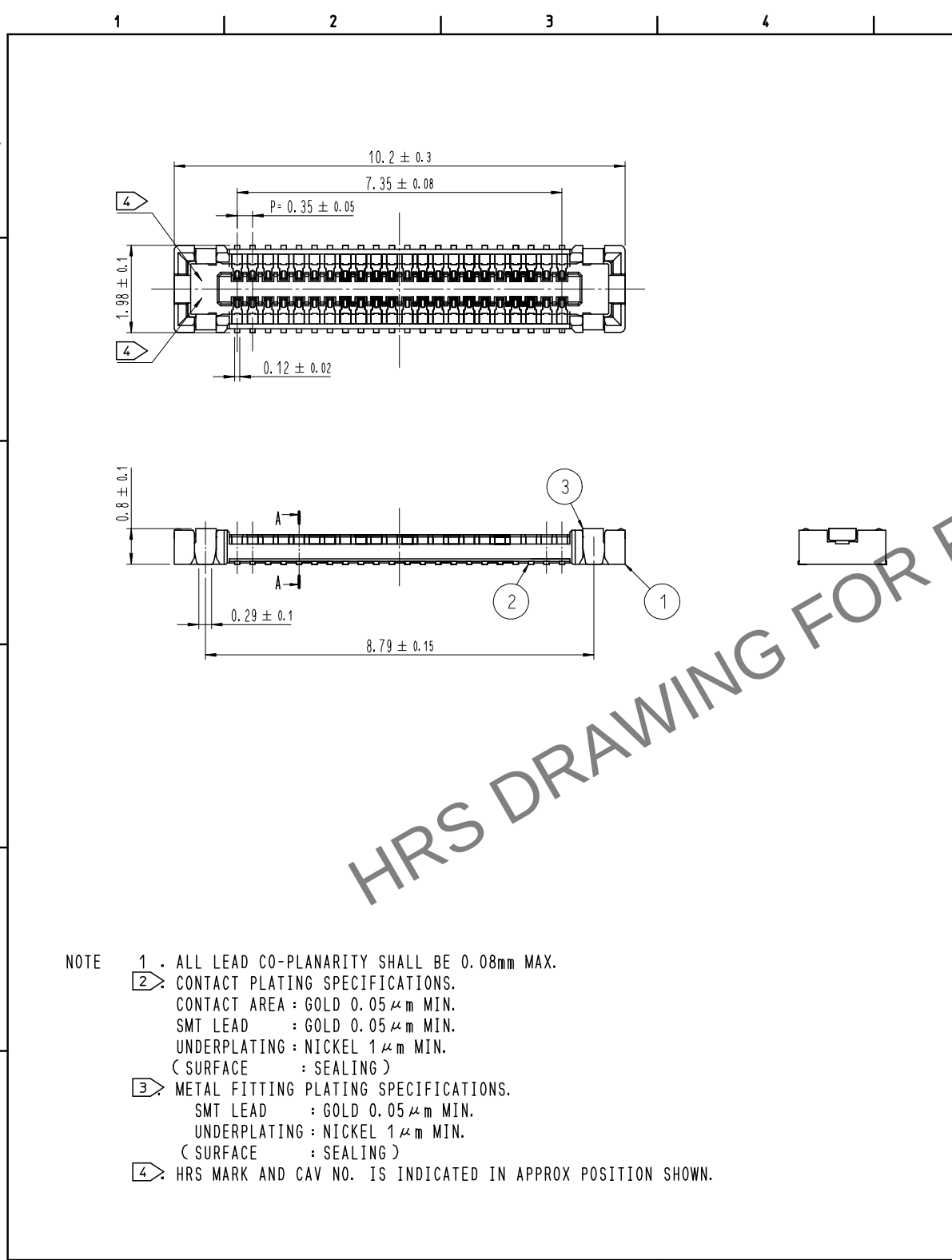
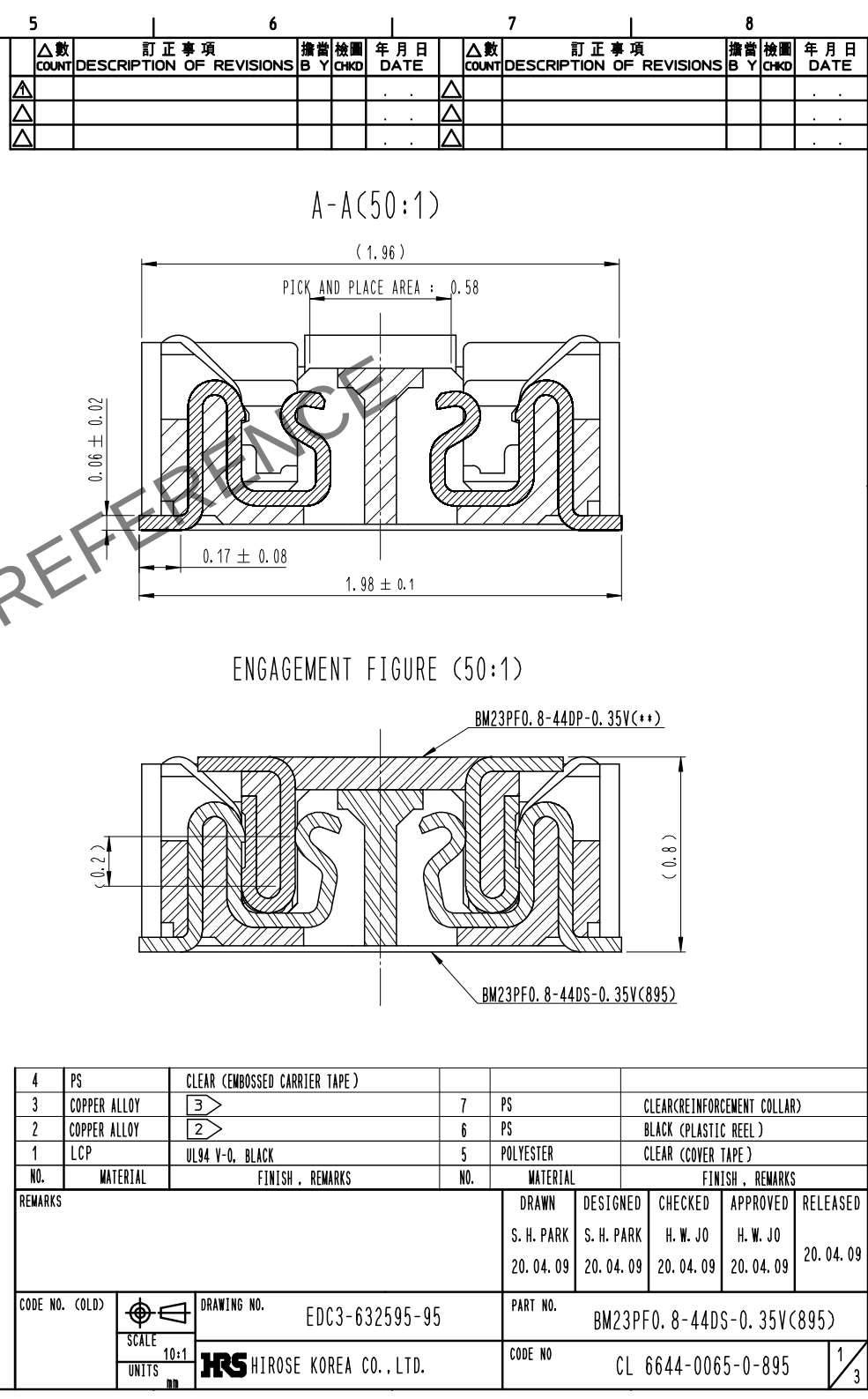


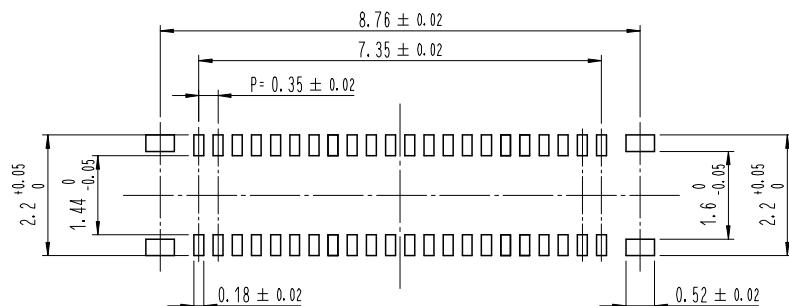


- NOTE
1. ALL LEAD CO-PLANARITY SHALL BE 0.08mm MAX.
  2. CONTACT PLATING SPECIFICATIONS.  
CONTACT AREA : GOLD  $0.05 \mu\text{m}$  MIN.  
SMT LEAD : GOLD  $0.05 \mu\text{m}$  MIN.  
UNDERPLATING : NICKEL  $1 \mu\text{m}$  MIN.  
( SURFACE : SEALING )
  3. METAL FITTING PLATING SPECIFICATIONS.  
SMT LEAD : GOLD  $0.05 \mu\text{m}$  MIN.  
UNDERPLATING : NICKEL  $1 \mu\text{m}$  MIN.  
( SURFACE : SEALING )
  4. HRS MARK AND CAV NO. IS INDICATED IN APPROX POSITION SHOWN.



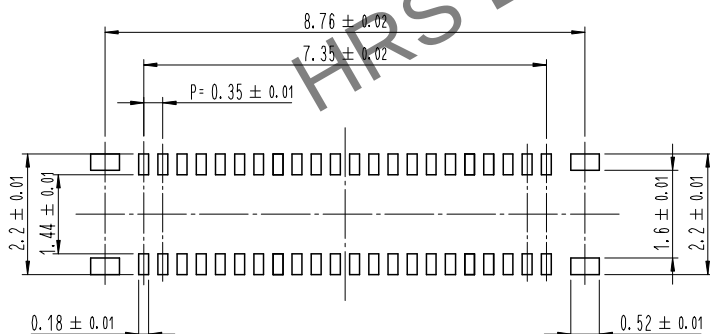
|                |                |                               |                    |            |                             |
|----------------|----------------|-------------------------------|--------------------|------------|-----------------------------|
| 4              | PS             | CLEAR (EMBOSSED CARRIER TAPE) | 7                  | PS         | CLEAR(REINFORCEMENT COLLAR) |
| 3              | COPPER ALLOY   | 3                             | 6                  | PS         | BLACK (PLASTIC REEL)        |
| 2              | COPPER ALLOY   | 2                             | 5                  | POLYESTER  | CLEAR (COVER TAPE)          |
| 1              | LCP            | UL94 V-0, BLACK               |                    |            |                             |
| NO.            | MATERIAL       | FINISH, REMARKS               | NO.                | MATERIAL   | FINISH, REMARKS             |
| REMARKS        |                |                               | DRAWN              | DESIGNED   | CHECKED                     |
|                |                |                               | S. H. PARK         | S. H. PARK | H. W. JO                    |
|                |                |                               | 20. 04. 09         | 20. 04. 09 | 20. 04. 09                  |
|                |                |                               | APPROVED           | RELEASED   |                             |
|                |                |                               | H. W. JO           |            | 20. 04. 09                  |
| CODE NO. (OLD) | DRAWING NO.    | PART NO.                      |                    |            |                             |
|                | EDC3-632595-95 | BM23PF0. 8-44DS-0.35V(895)    |                    |            |                             |
| SCALE          | 10:1           | CODE NO                       | CL 6644-0065-0-895 |            |                             |
| UNITS          | mm             |                               |                    |            | 1/3                         |

# 6 RECOMMENDED PCB LAYOUT

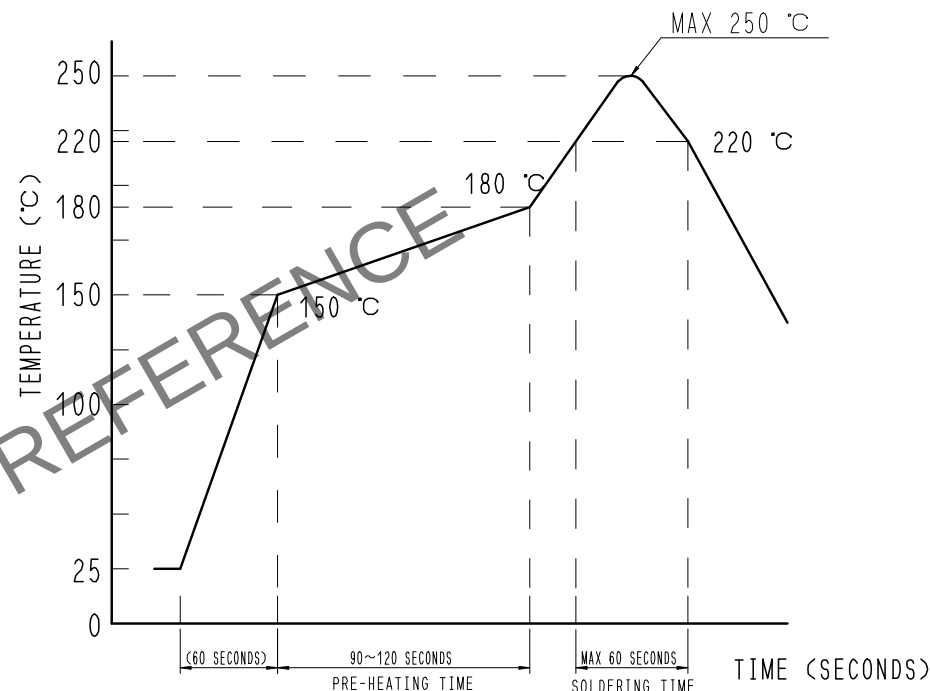


## RECOMMENDED METAL MASK DIMENSIONS

METAL MASK THICKNESS :  $100 \mu\text{m}$



## 5 RECOMMENDED REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE.



REFLOW METHOD:  $\text{N}_2$  REFLOW

NUMBER OF REFLOW CYCLES: 2 CYCLES MAX.

1) REFLOW TIME

DURATION ABOVE 220 $^{\circ}\text{C}$ : 60 SEC MAX.  
 (PEAK TEMPERATURE: 250 $^{\circ}\text{C}$  MAX)

2) PRE-HEAT TIME

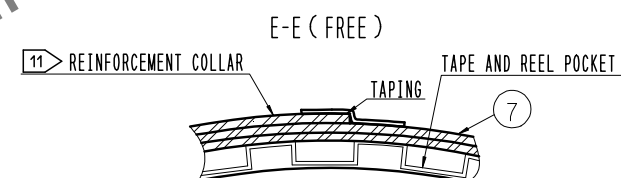
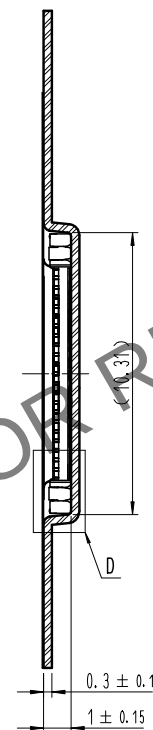
PRE-HEAT TEMPERATURE(MIN): 150 $^{\circ}\text{C}$   
 PRE-HEAT TEMPERATURE(MAX): 180 $^{\circ}\text{C}$   
 PRE-HEAT TIME: 90~120 SEC.

5 THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE. ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE. THEREFORE, A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.

6 PLEASE CONTACT US IN CASE YOU WILL MAKE DIFFERENT SETTINGS FROM OUR RECOMMENDATION.

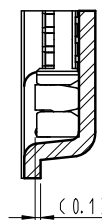
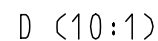
|       |                        |                |          |                            |
|-------|------------------------|----------------|----------|----------------------------|
|       | DRAWING NO.            | EDC3-632595-95 | PART NO. | BM23PF0. 8-44DS-0.35V(895) |
|       | SCALE                  | 10:1           | CODE NO  | CL 6644-0065-0-895         |
| UNITS | HIROSE KOREA CO., LTD. |                |          | 2/3                        |

C-C (5:1)



|                      |                           |
|----------------------|---------------------------|
| SUPPLIER             |                           |
| QUANTITY             |                           |
| PART NO.             |                           |
| CODE NO.             |                           |
| DATE OF MANUFACTURED |                           |
| 生産月日                 | 年 月 日                     |
| 図番                   | *** ** *                  |
| 品名                   | BM23PF0. 8-44DS-0. 35VC89 |
| 納入数量                 | 1, 000個                   |
| 納入者                  | HIROSE KOREA              |

10. AFTER PACKAGING. ROLL 2 METERS OF THE REINFORCEMENT COLLAR TO OUTER CIRCUMFERENCE OF TAPE AND REEL POCKET. AND TAPE DOWN AT THE END THE COLLAR.



10 TAPING(FREE)

